ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES* international and I	position De IPC, Bannockt Pan-American co	claration ourn, Illinois. <i>A</i> opyright conve	All rights reserved untions.	under both	This docume level parts, th	ent is a declaration he declaration er	n of the substanc compasses all lo	es within the ma wer level materia	nufacturer liste ls for which th	ed item. Note: i e manufacturer	f the item is an as has engineering	ssembly with low responsibility.	
				Form Type Distribute					s Materials and	rials and Mfg Information			
upplier Information													
ompany name*	Company unique ID			l	Unique ID Authority				Response Date*				
nsemi									2024-05-03				
Contact Name T			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Representative]	Phone - Representative*			Emai	Email - Representative*				
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	NFAL50	NFAL5065L4B 650V/50A I		Large DIP		2024-05-03		СРА		47932.68	mg	Each	
Ianufacturing Proccess Inform	ation												
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal		ase Alloy J-STD-020 MSL		L Rating	Peak Proce	Peak Process Body Temperat		at Peak Tempe	erature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30	see	conds 3				
omments													
or more information regarding materi	al composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	7836.77	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1449.8025	mg
			Supplier	Copper (Cu)	7440-50-8		6386.9673	mg
Die	126.17	mg	Supplier	Silicon (Si)	7440-21-3		126.17	mg
Die Attach	101.19	mg	Supplier	Silver (Ag)	7440-22-4		2.5298	mg
			Supplier	Tin (Sn)	7440-31-5		93.6008	mg
			Supplier	Copper (Cu)	7440-50-8		5.0595	mg
Die Attach Epoxy	9.58	mg	Supplier	Silver (Ag)	7440-22-4		8.8136	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.7664	mg
Die Attach Solder	20.14	mg	Supplier	Silver (Ag)	7440-22-4		0.5035	mg
			А	Lead (Pb)	7439-92-1	7a	18.6295	mg
			Supplier	Tin (Sn)	7440-31-5		1.007	mg
Lead Frame	3926.73	mg	Supplier	Zinc (Zn)	7440-66-6		4.7121	mg
			Supplier	Iron (Fe)	7439-89-6		92.2782	mg
			Supplier	Copper (Cu)	7440-50-8		3828.5618	mg
			Supplier	Phosphorus (P)	7723-14-0		1.178	mg
Mold Compound-Black	35664.24	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		1426.5695	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		1426.5695	mg
			Supplier	Carbon Black (C)	1333-86-4		178.3212	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		30849.5664	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		356.6424	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1426.5695	mg
Plating	26.97	mg	Supplier	Tin (Sn)	7440-31-5		26.97	mg
Wire Bond - Al	220.14	mg	Supplier	Aluminum (Al)	7429-90-5		220.14	mg
Wire Bond - Au	0.75	mg	Supplier	Gold (Au)	7440-57-5		0.75	mg